SMDCT10N090LST3H

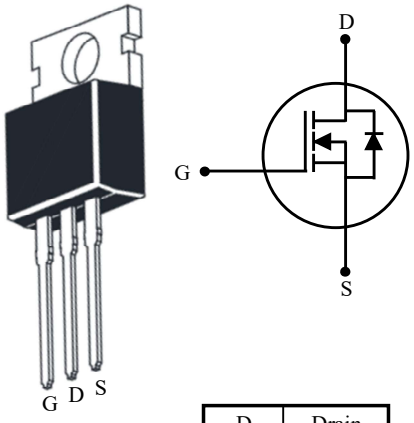
N-Channel Enhancement Mode Field Effect Transistor

FEATURES

· Suffix "H" indicates Halogen-free parts, ex.SMDCT10N090LST3H

PIN CONFIGURATION

TO-220



D	Drain
G	Gate
S	Source

Maximum Ratings(T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	±20	
Drain Current T_C=25℃	I_D	66.0	A
Drain Current T_C=100℃		41.5	
Pulsed Drain Current (Note 1)	I_{DM}	260	A
Avalanche Current	I_{AS}	23.8	A
Single Pulse Avalanche Energy (Note 2)	E_{AS}	28.3	mJ
Power Dissipation T_C=25℃	P_D	69.4	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	60	℃/W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.8	℃/W
Operating Junction and Storage Temperature Range	T_J,T_{stg}	- 55 to + 150	℃

Note:

1. The data tested by pulsed, pulse width ≦100μs, duty cycle ≦2%, Reptitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C

2. Limited by $T_{J(MAX)}$, starting T_J=25℃, L=0.1mH, R_g=25Ω, I_{AS}=23.8A, V_{GS}=10V.

SMDCT10N090LST3H

N-Channel Enhancement Mode Field Effect Transistor

Electrical Characteristics(T_A=25 ℃ unless otherwise specified)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	I_D=250μA	$V_{(BR)DSS}$	100	-	-	V
Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	$V_{GS(th)}$	1.2	-	2.5	V
Zero Gate Voltage Drain Current	V_{DS}=80V	I_{DSS}	-	-	1	μA
Gate Leakage Current	V_{GS}=±20V	I_{GSS}	-	-	±0.1	μA
Drain-Source On-Resistance	V_{GS}=10V, I_D=15A	$R_{DS(on)}$	-	8.5	10.5	mΩ
	V_{GS}=4.5V, I_D=10A		-	-	13.9	
Forward Transconductance	V_{DS}=5V, I_D=10A	g_{FS}	-	27	-	S
Dynamic						
Gate Resistance	V_{DS}=0V, V_{GS}=0V, f=1MHz	R_g	-	1	-	Ω
Total Gate Charge	V_{DS}=50V, V_{GS}=4.5V, I_D=15A	Q_g	-	23	-	nC
	V_{DS}=50V, V_{GS}=10V, I_D=15A		-	42	-	
Gate-Source Charge		Q_{gs}	-	6	-	
Gate-Drain Charge		Q_{gd}	-	13	-	
Input Capacitance	V_{DS}=50V, V_{GS}=0V, f=1MHz	C_{iss}	-	1753	-	pF
Output Capacitance		C_{oss}	-	334	-	
Reverse Transfer Capacitance		C_{rss}	-	34	-	
Turn on Delay Time	V_{DS}=50V, I_D=15A V_{GS}=10V, R_g=3.3Ω	$t_{d(on)}$	-	18.0	-	ns
Turn on Rise Time		t_r	-	30.0	-	
Turn off Delay Time		$t_{d(off)}$	-	19.0	-	
Turn off Fall Time		t_f	-	4.5	-	
Drain-Source Body Diode						
Diode Forward Voltage	V_{GS}=0V, I_S=1A	V_{SD}	-	-	1.2	V
Diode Continuous Forward Current	-	I_S	-	-	66	A
Diode Pulse Current		I_{SM}	-	-	260	A
Reverse Recovery Time	I_S=15A, di/dt=100A/μs	t_{rr}	-	40	-	ns
Reverse Recovery Charge		Q_{rr}	-	51	-	nC

RATINGS AND CHARACTERISTIC CURVES

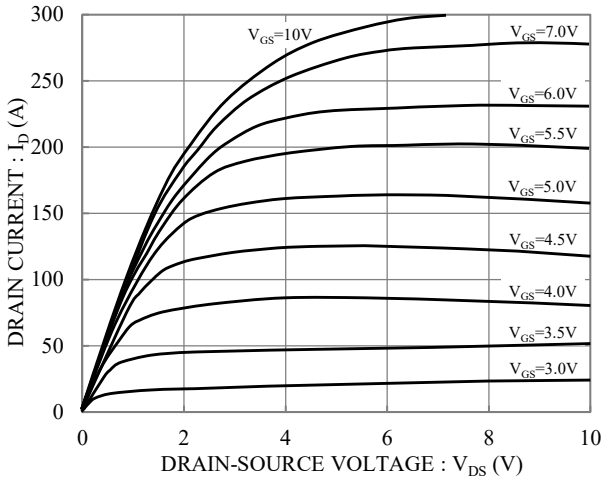


Fig.1 Typical Output Characteristics

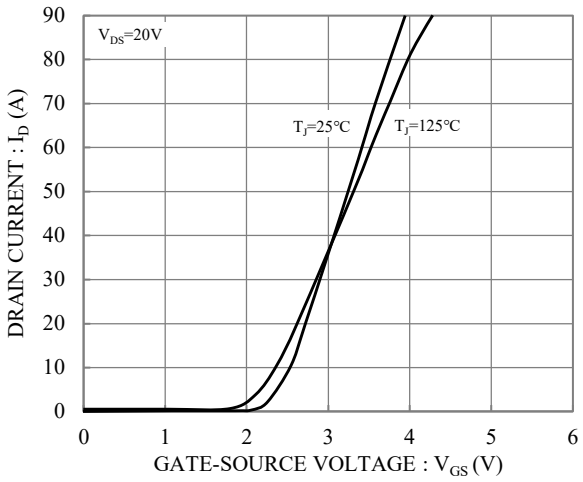


Fig.2 Typical Transfer Characteristics

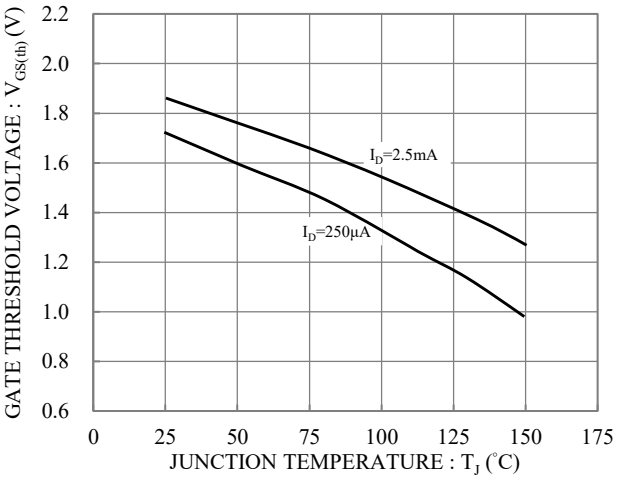


Fig.3 Gate Threshold Voltage vs. Junction Temperature

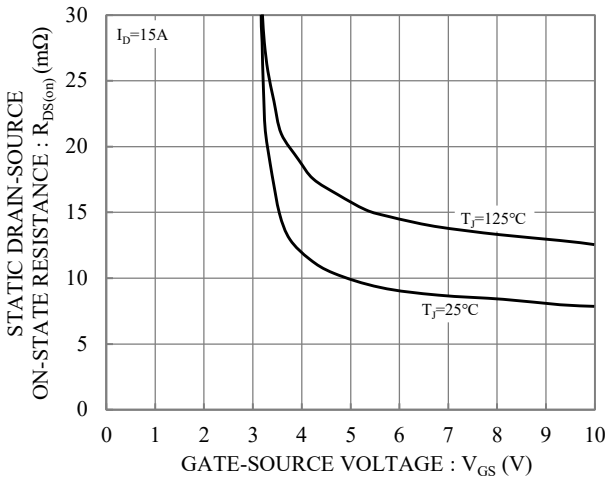


Fig.4 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

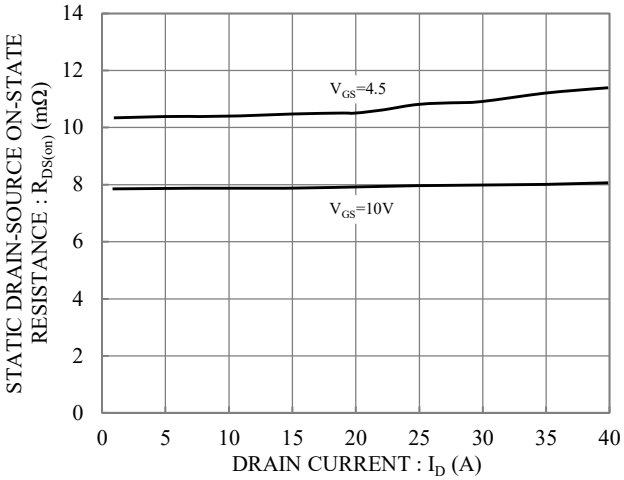


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

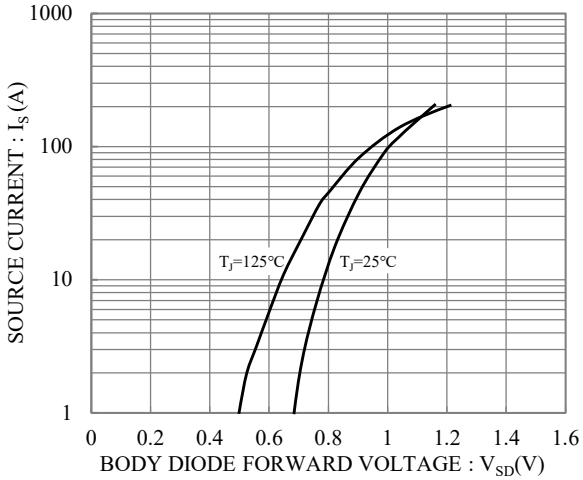


Fig.6 Body Diode Forward Voltage vs. Source Current

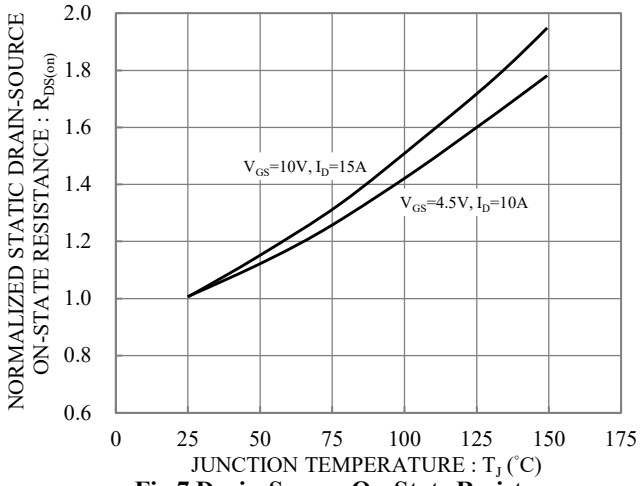


Fig.7 Drain-Source On-State Resistance vs. Junction Tempearture

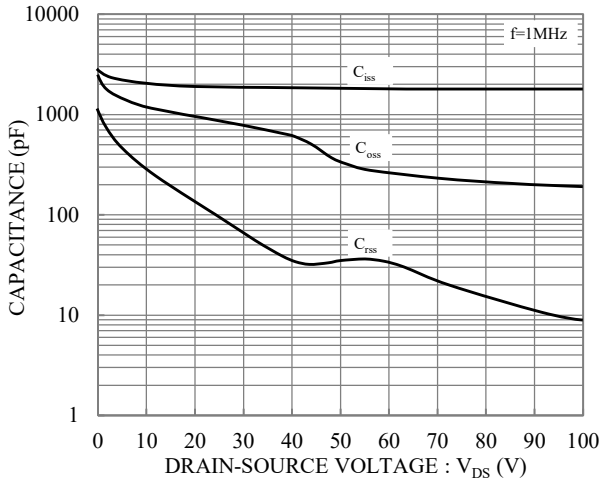


Fig.8 Capacitance vs. Drain-Source Voltage

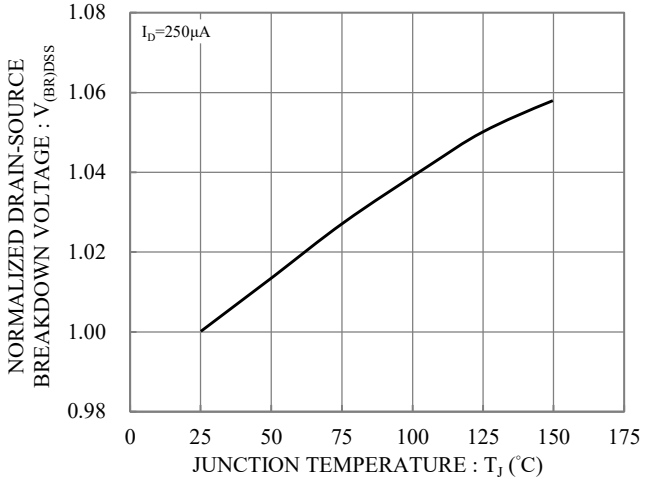


Fig.9 Breakdown Voltage vs. Junction Temperature

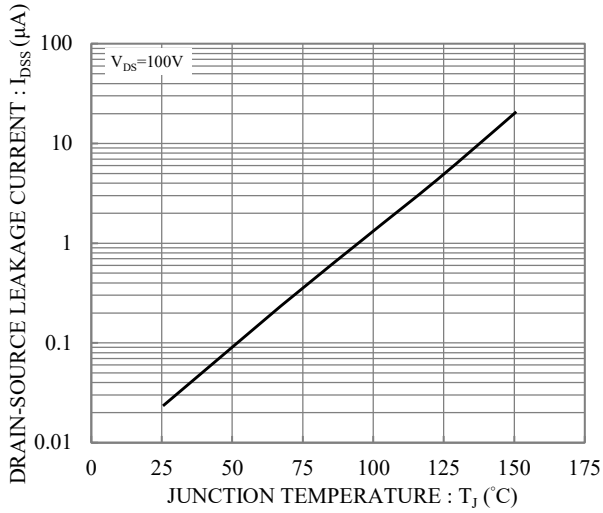


Fig.10 Drain-Source Leakge Current vs. Junction Temperature

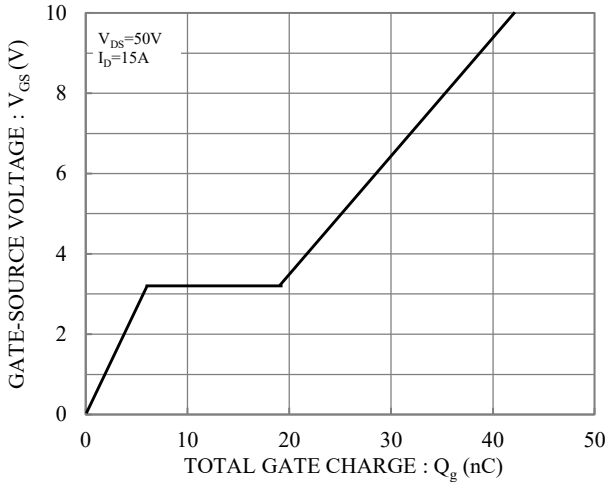


Fig.11 Gate Charge Characteristics

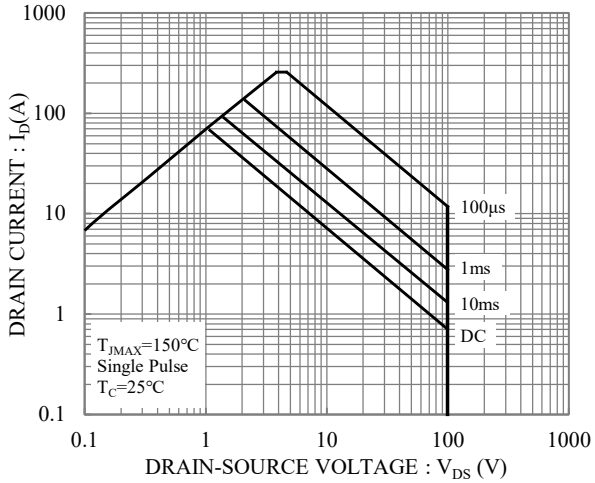


Fig.12 Safe Operation Area

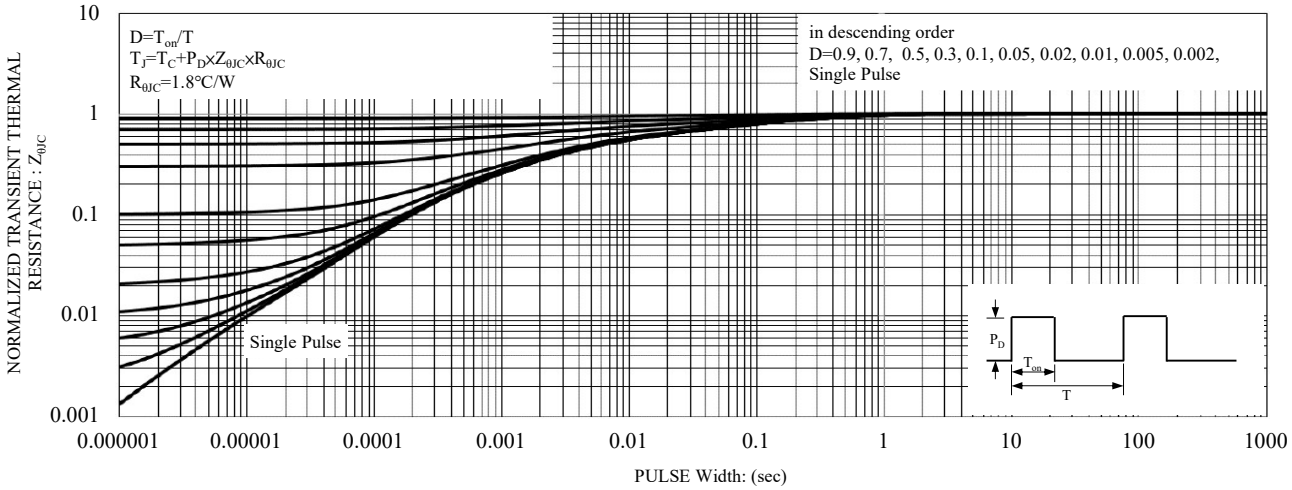


Fig.13 Maximum Transient Thermal Impedance

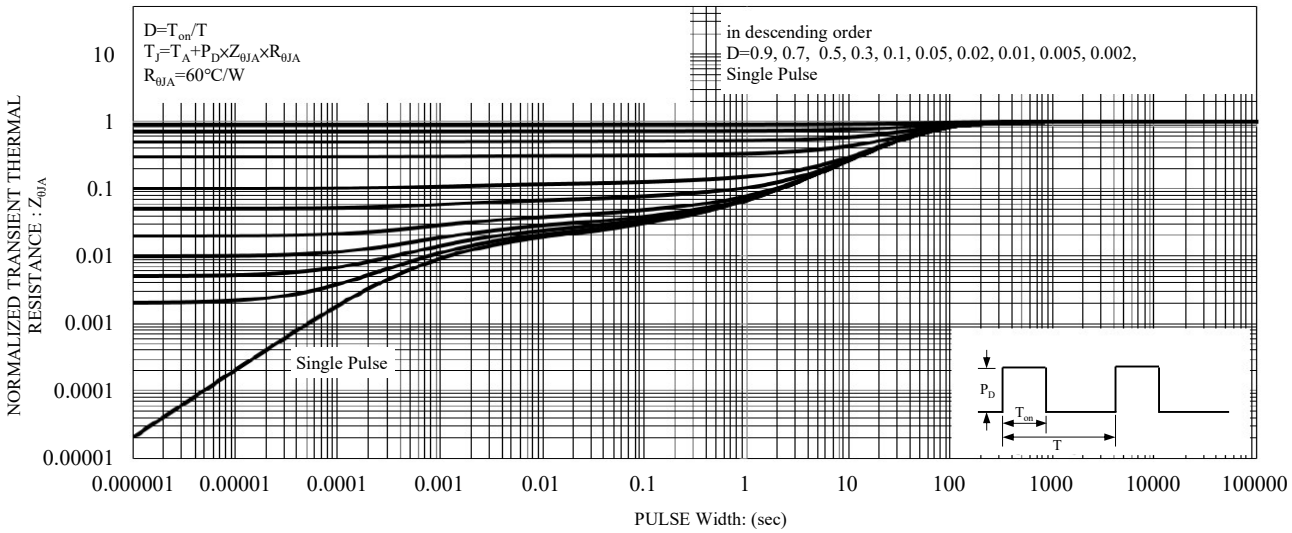
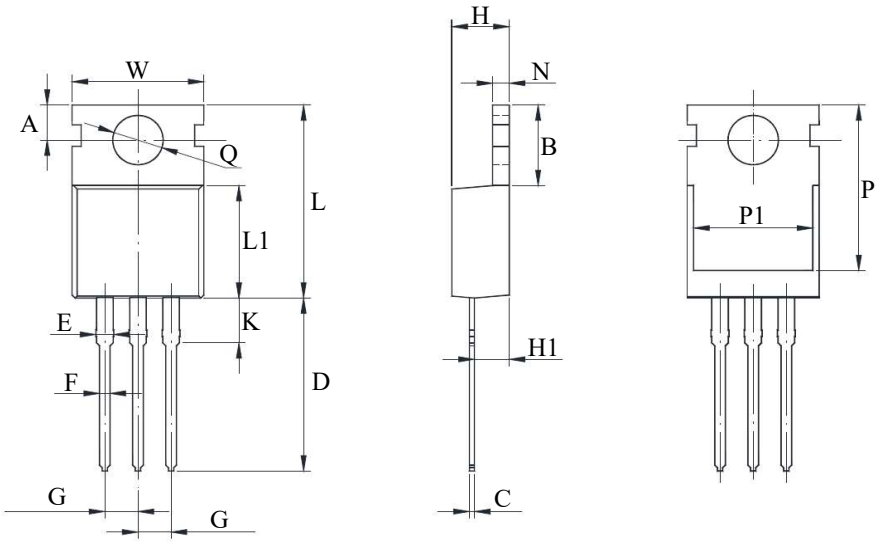


Fig.14 Maximum Transient Thermal Impedance

PACKAGE DIMENSION

TO-220



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	2.70	2.90	0.106	0.114
B	6.40	6.80	0.252	0.268
C	0.30	0.70	0.012	0.028
D	11.00	15.00	0.433	0.591
E	1.10	1.50	0.043	0.059
F	0.70	0.90	0.028	0.035
G	2.54 TYP.		0.100 TYP.	
W	9.80	10.20	0.386	0.402
H	4.30	4.70	0.169	0.185
H1	2.20	2.50	0.087	0.098
K	2.70	3.10	0.106	0.122
L	14.80	16.80	0.583	0.661
L1	9.00	9.40	0.354	0.370
N	1.20	1.40	0.047	0.055
P	12.70	13.30	0.500	0.524
P1	7.60	8.20	0.299	0.323
Q	3.50	3.70	0.138	0.146